

RAD7160-NNAx Power MOSFET Die

Preliminary Data Sheet

January, 2013

www.aeroflex.com/MOSFETS**FEATURES**

- ❑ 100V breakdown voltage
- ❑ 60A current rating
- ❑ 0.013Ω $R_{DS(on)}$
- ❑ 150nC gate charge
- ❑ -55°C to +125°C temperature range
- ❑ Operational Environment radiation testing to MIL-STD-750
 - Total-dose: 100 krad(Si)
 - SEGR/SEB immune to Xe at full rated drain potential
- ❑ Bare Die
 - Prototype, EMs and Class S
- ❑ Drop-in compatible with industry standards
- ❑ Class S MOSFETs built to your custom flow

INTRODUCTION

Aeroflex RAD's new radiation tolerant power MOSFETs are now available in die, seven standard package options and custom packaging for HiRel environments. Applications within military, aerospace, medical, nuclear power generation, high energy physics research laboratories can benefit from the use of this new series of MOSFETs. Aeroflex's Power MOSFETs are radiation tolerant to 100 krad(Si) and SEGR/SEB immune to their full rated breakdown potential.

Operational power losses are minimized by Aeroflex's ideal combination of low $R_{DS(on)}$ and gate charge. Die size is optimized for maximum current rating while meeting industry norms. These units are suitable for standalone and hybrid applications.

The RAD7160-NNAx are well suited for low loss switching applications, such as DC-to-DC Converters and solid-state relays. They are drop-in compatible with industry standards.

ELECTRICAL CHARACTERISTICS (Case temperature (T_c) = 25°C unless otherwise specified)

CHARACTERISTICS		TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
Drain-Source Breakdown Voltage	BV_{dss}	$V_{gs} = 0V, I_d = 1mA$	100	-	-	V
Gate-Threshold Voltage	$V_{gs(th)}$	$V_{ds} = V_{gs}, I_d = 1.0mA$	2.0	-	4.0	V
Gate-Body Leakage	I_{gss}	$V_{gs} = \pm 20V$	-	-	100	nA
Zero-Gate Leakage	I_{dss1}	$V_{ds} = 80V, V_{gs} = 0V$	-	-	25	μA
Drain Current	I_{dss2}	$V_{ds} = 80V, V_{gs} = 0V, T_c = 125^\circ C$	-	-	250	
Drain-Source On Resistance	$R_{DS(on)}$	$V_{gs} = 12V, I_d = 48A$	-	-	0.013	ohms
Gate Charge at 12V	$Q_g(12)$	$V_{gs} = 12V$	-	-	150	nC
		$I_d = 60A$ $V_{dd} = 50V$				
Diode Forward Voltage	V_{sd}	$I_d = 60A, V_{gs} = 0V$	0.6	-	1.2	V
Junction-to-Case	$R_{\theta jc}$	NA/Die	-	-	-	°C/W

POST-RADIATION ELECTRICAL CHARACTERISTICS

CHARACTERISTICS	TEST CONDITIONS	LIMITS		UNITS	
		MIN	MAX		
Drain-Source Breakdown Voltage ^{3,4}	BV _{DSS}	V _{GS} = 0V, I _D = 1mA	100	-	V
Gate-Threshold Voltage ^{3,4}	V _{GS(th)}	V _{GS} = V _{DS} , I _D = 1.0mA	1.5	4.0	V
Gate-Body Leakage Forward ^{2,3,4}	I _{GSS}	V _{GS} = ±20, V _{DS} = 0V	-	100	nA
Zero-Gate Voltage Drain Current ^{3,4}	I _{DSS}	V _{GS} = 0V, V _{DS} = 80V	-	25	μA
Drain-Source On-Resistance ^{1,3,4}	R _{DS(on)}	V _{GS} = 12V, I _{DS} = 48A	-	0.013	ohms

Notes:* for die products, the maximum current may be limited by packaging

1. Pulse test, 300μs max
2. Absolute value
3. Gamma = 100 krad(Si)
4. Gamma irradiation bias at both V_{GS} = 12V, V_{DS} = 0V and V_{GS} = 0V, V_{DS} = 80% BV_{DSS}

SEE (SINGLE-EVENT-EFFECTS)

CHARACTERISTICS	SYMBOL	ENVIRONMENT ¹				MAX VDS BIAS (V) ²
		ENERGY (MeV)	TYPICAL LET (MeV/cm ² /mg)	TYPICAL RANGE (μ)	APPLIED VGS BIAS (V)	
Single Event Effects - Safe Operating Area	Kr	906	30	113	-10	100
	Xe	1232	59	99	-5	100

Notes:

1. Fluence = 1E6 ions/cm² (typical), T = 25°C
2. Does not exhibit Single Event Burnout (SEB) or Single Event Gate Rupture (SEGR).

DIE FEATURES

- Die Size
- 0.279" x 0.324" Nominal
- Gate Pad
- .010" x 0.22" Nominal
- Source Pad
- 0.109" x 0.270" Nominal
- Die Thickness
- 14 mils
- Top Metal
- 40kÅ (±10%) Al 1% Si
- Back Metal
- Ti(2kÅ)NiV(10kÅ)Ag(2kÅ) (±10%)

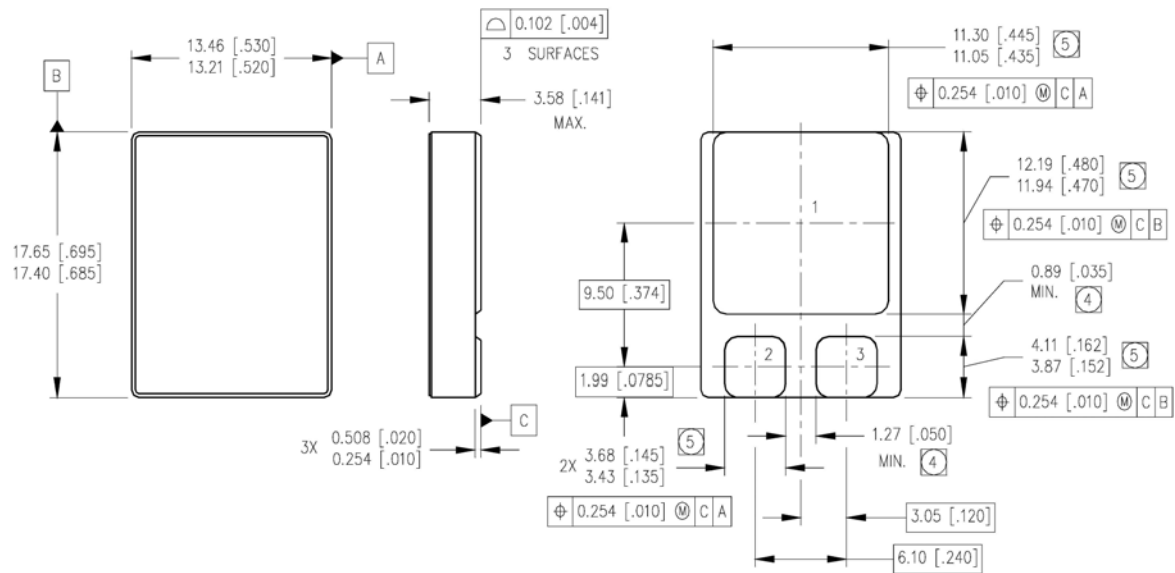
ELECTRICAL TESTING AT WAFER PROBE:

ITEM	VOLTAGE	CURRENT	LOWER LIMIT	UPPER LIMIT	LOWER SPEC	UPPER SPEC	UNIT
igss	Vgs=5V			100			uA
igss	Vgs=20V			100		100	nA
igss	Vgs=30V			1			uA
idss	Vds=80V			2		25	uA
idss	Vds=100V			10		1000	uA
bvdss		Ids=1mA	100		100		V
r _{don}	Vgs=12V	Ids=0.5A		.01		.013	mΩ
r _{don}	Vgs=12V	Ids=2A		.01		.013	mΩ
v _{sd}		I _{sd} =2A	0.6	1.2	0.6	1.8	V
v _{th}		I _{ds} =250μA	2.7	3.9	2.00	4.00	V
igssr	Vgs=-20V			100		100	nA
igssr	Vgs=-30V			1			uA

AEROFLEX RAD RAD7160-NNAx PART NUMBERING:

PART #	BREAKDOWN POTENTIAL (V)	R _{DS(on)} (mΩ)	DRAIN CURRENT (A)	GATE CHARGE (nC)	TID LEVEL (krad(Si))	SEE	Die size	PKG	SCREENING
RAD7160-NNAP	100	13	60	150	100	Xe	6	SMD2	Prototype
RAD7160-NNAE	100	13	60	150	100	Xe	6	SMD2	EM
RAD7160-NNAS	100	13	60	150	100	Xe	6	SMD2	Space

Case Outline and Dimensions — SMD-2



NOTES:

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
- (4) DIMENSION INCLUDES METALLIZATION FLASH.
- (5) DIMENSION DOES NOT INCLUDE METALLIZATION FLASH.

PAD ASSIGNMENTS

- 1 = DRAIN
- 2 = GATE
- 3 = SOURCE

Aeroflex RAD- Datasheet Definition

Advanced Datasheet - Product In Development

Preliminary Datasheet - Shipping Prototypes

Datasheet - Class S Compliant, QML or JAN

COLORADO

Toll Free: 800-645-8862
Fax: 719-594-8468

INTERNATIONAL

Tel: 805-778-9229
Fax: 805-778-1980

NORTHEAST

Tel: 603-888-3975
Fax: 603-888-4585

SE AND MID-ATLANTIC

Tel: 321-951-4164
Fax: 321-951-4254

WEST COAST

Tel: 949-362-2260
Fax: 949-362-2266

CENTRAL

Tel: 719-594-8017
Fax: 719-594-8468

www.aeroflex.com info-ams@aeroflex.com

Aeroflex RAD (Aeroflex) reserves the right to make changes to any products and services herein at any time without notice. Consult Aeroflex or an authorized sales representative to verify that the information in this data sheet is current before using this product. Aeroflex does not assume any responsibility or liability arising out of the application or use of any product or service described herein, except as expressly agreed to in writing by Aeroflex; nor does the purchase, lease, or use of a product or service from Aeroflex convey a license under any patent rights, copyrights, trademark rights, or any other of the intellectual rights of Aeroflex or of third parties.



Our passion for performance is defined by three attributes represented by these three icons: solution-minded, performance-driven and customer-focused